

Title (en)

METHOD FOR MAKING DIE BOARDS, AND MATERIALS AND APPARATUS FOR PRACTICING THE METHOD

Title (de)

VERFAHREN ZUM HERSTELLEN EINES STANZWERKZEUGES SOWIE MATERIALIEN UND VORRICHTUNG ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)

PROCEDE DE FABRICATION DE MATRICES DE DECOUPAGE/PLIAGE ET SES MATERIAUX ET APPAREILS DE MISE EN OEUVRE

Publication

EP 1198328 A4 20080102 (EN)

Application

EP 01930679 A 20010424

Priority

- US 0113124 W 20010424
- US 55857500 A 20000426

Abstract (en)

[origin: WO0181051A1] In a die board (10) for cutting and/or creasing sheet-type work material, a base (12) is provided that includes a first upper surface (13) and a second lower surface (14). At least one slot (16) extends along the first upper surface and includes a first slot section (18) extending from said first upper surface at least part-way through the die board base. The at least one slot also includes a second slot section (20) extending from said second lower surface at least part-way through the die board base. The first and second slot sections each have a width with at least one of the slot section widths being adapted to grip and retain at least one die-board rule (22).

IPC 1-7

B26D 7/00

IPC 8 full level

B27C 5/02 (2006.01); **B26F 1/44** (2006.01); **B27G 13/14** (2006.01)

CPC (source: EP)

B26F 1/44 (2013.01); **B26F 1/40** (2013.01); **B26F 2001/4463** (2013.01)

Citation (search report)

- [X] US 5816753 A 19981006 - HALL JAMES H [US]
- [X] US 5823720 A 19981020 - MOORE RICHARD A [US]
- [X] US 4449865 A 19840522 - YANKOVOY ALEXANDER [US], et al
- [X] US 4662803 A 19870505 - ARNOLD WESLEY C [US]
- See references of WO 0181051A1

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

WO 0181051 A1 20011101; AU 5718801 A 20011107; EP 1198328 A1 20020424; EP 1198328 A4 20080102; JP 2003531035 A 20031021

DOCDB simple family (application)

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